

ABSTRACT OF THE DISCLOSURE

A system and method for reducing the amount of contaminants that come into contact with wafer substrates during the production of integrated circuit devices. The system allows for uniform overflow of processing liquid from a process tank while preventing contaminants from reentering the process tank and contacting the wafers. The system in one aspect comprises an inner weir with a top surface, and overflow wall with at least one recess having a bottom, and a structure, the structure connecting the overflow wall and the inner weir to form a drainage basin with at least one drain hole; wherein the top surface of the inner weir is below the bottom of the at least one recess.